



Material Content Data Sheet



Sales Product Name		SGD02N120		Issued		20. July 2018		
MA#		MA000207618						
Package		PG-TO252-3-11		Weight*		365.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.530	0.69	0.69	6928	6928
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		177	
	non noble metal	iron	7439-89-6	0.215	0.06		590	
	non noble metal	copper	7440-50-8	215.017	58.87	58.95	588742	589509
	non noble metal	aluminium	7429-90-5	0.494	0.14	0.14	1354	1354
wire	non noble metal	aluminium	7429-90-5	0.494	0.14	0.14	1354	1354
encapsulation	organic material	carbon black	1333-86-4	1.215	0.33		3326	
	inorganic material	antimonytrioxide	1309-64-4	2.430	0.67		6653	
	plastics	brominated resin	-	2.430	0.67		6653	
	plastics	epoxy resin	-	24.296	6.65		66525	
	inorganic material	silicondioxide	60676-86-0	91.110	24.95	33.27	249470	332627
leadfinish	non noble metal	tin	7440-31-5	3.740	1.02	1.02	10241	10241
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	249	250
solder	non noble metal	tin	7440-31-5	0.048	0.01		130	
	noble metal	silver	7440-22-4	0.059	0.02		163	
	non noble metal	lead	7439-92-1	2.271	0.62	0.65	6219	6512
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		53	
	non noble metal	copper	7440-50-8	19.177	5.25	5.26	52510	52579
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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